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GTT Group Representing Prolific Inventors in Divestment of High-Performance Computing Patent Portfolio

Portland, Oregon (June 2017) -- Global Technology Transfer Group, Inc. (GTT Group), the premier provider of patent analysis and transaction advisory services to information and communication technology companies worldwide, announces the availability of a patent portfolio related to semiconductor interconnect technologies essential for high-performance computing applications, such as graphics, networking, artificial intelligence, deep learning, advanced data centers and autonomous vehicles.

The portfolio was developed by a pair of inventors who each have over 30 years of experience in high speed interconnect and electronic circuit design, as well as intellectual property development and protection. The inventors have over 85 patents in their name and have held senior technical positions in leading semiconductor companies.

The portfolio contains 11 global assets in one patent family, including four issued US patents and one pending US application. Other jurisdictions with patent coverage are China, Europe, Japan and Singapore.

The patented technology provides a high bandwidth, low latency, modular interface between a CPU and associated peripheral circuitry such as high-speed communication ports or memory channels. The claimed technology can be implemented in numerous applications, including high-performance computing, servers and embedded processors.

One key patent in the portfolio relates to an interposer, an electrical interface used to spread connections to a wider pitch or to reroute connections. The patent addresses problems that arise in routing signals on a motherboard between various electronic devices, such as may be caused by connection length, discontinuities in trace geometries and electrical properties as may result from manufacturing of the motherboard and installation of the devices, as well as properties of the circuits themselves. The patent proposes a solution whereby an interposer board is used to mitigate these problems.

An interposer, as claimed in the patent, may be used in a multi-chip module (MCM) to provide the interconnect between the various chips in the module. The MCM may then be mounted to a circuit substrate to provide additional circuitry, such as power supply circuitry, and to provide additional mechanical strength. For example, interposers are currently being used in high-bandwidth memory (HBM) stacks between the processor to fully realize performance. GTT Group has prepared evidence of use materials on major market participants to illustrate adoption of the patent.

“We are grateful for the opportunity to be working with inventors that have made such pivotal contributions to the microelectronics industry,” said GTT Group Director of Asset Services, Andrew Godsey. “Their inventions are enabling the performance increases that are driving the advancements in high-performance computing.”

To receive more information about this opportunity, please contact Andrew Godsey. All inquiries will be kept strictly confidential.

GTT Group is approaching potential buyers and providing materials explaining the strategic advantages of acquiring the portfolio. In addition, GTT Group’s subject matter experts will be available to discuss the strengths of the patents and applications in the market. Offers to acquire the portfolio should be submitted by August 2017.

About Global Technology Transfer Group, Inc.

Global Technology Transfer Group, Inc. is a patent analysis and transaction advisory firm. The company’s corporate headquarters are in Portland, Oregon.

For more information, visit GTT Group at: www.gttgrp.com

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